



THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Takashi Kumamoto et al.
Serial No. : 09/878,123
Filed : June 8, 2001
Title : CHIP LEAD FRAMES

Art Unit : 2827
Examiner : Luan C. Thai

Commissioner for Patents
Washington, D.C. 20231

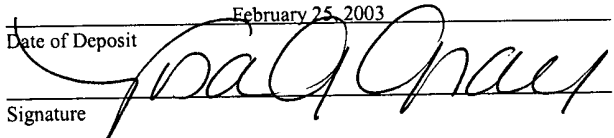
RESPONSE TO OFFICE ACTION DATED 8/30/02

Introductory comments

In response to the action dated August 30, 2002, please amend the application as detailed below. Amendments are being presented in the format described in the Official Gazette, December 17, 2002 and begin on the following page.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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Lisa G. Gray
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Applicant : Takashi Kumamoto et al.
Serial No. : 09/878,123
Filed : June 8, 2001
Page : 2

Attorney's Docket No.: 10559-445001 / P9482X

In the title

Please replace the title with:

-- ENCAPSULATED PACKAGING FOR CHIP LEAD FRAMES--